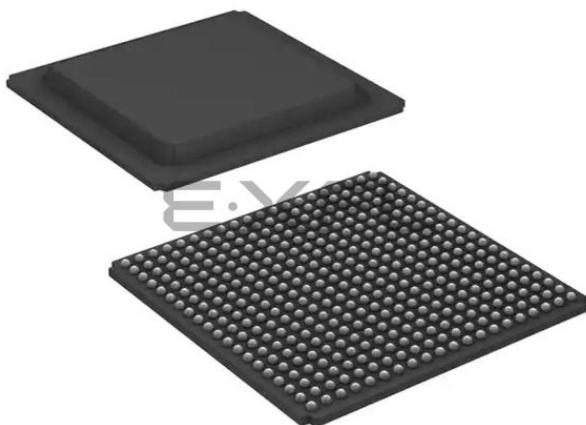




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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	896
Number of Logic Elements/Cells	8064
Total RAM Bits	368640
Number of I/O	311
Number of Gates	400000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	400-BGA
Supplier Device Package	400-FBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s400a-4fg400i

Production Status

Table 3 indicates the production status of each Spartan-3A FPGA by temperature range and speed grade. The table also lists the earliest speed file version required for creating

a production configuration bitstream. Later versions are also supported.

Table 3: Spartan-3A FPGA Production Status (Production Speed File)

Temperature Range		Commercial (C)		Industrial
Speed Grade		Standard (–4)	High-Performance (–5)	Standard (–4)
Part Number	XC3S50A	Production (v1.35)	Production (v1.35)	Production (v1.35)
	XC3S200A	Production (v1.35)	Production (v1.35)	Production (v1.35)
	XC3S400A	Production (v1.36)	Production (v1.36)	Production (v1.36)
	XC3S700A	Production (v1.34)	Production (v1.35)	Production (v1.34)
	XC3S1400A	Production (v1.34)	Production (v1.35)	Production (v1.34)

Package Marking

Figure 2 provides a top marking example for Spartan-3A FPGAs in the quad-flat packages. Figure 3 shows the top marking for Spartan-3A FPGAs in BGA packages. The markings for the BGA packages are nearly identical to those for the quad-flat packages, except that the marking is rotated with respect to the ball A1 indicator.

The “5C” and “4I” Speed Grade/Temperature Range part combinations may be dual marked as “5C/4I”. Devices with a single mark are only guaranteed for the marked speed grade and temperature range.

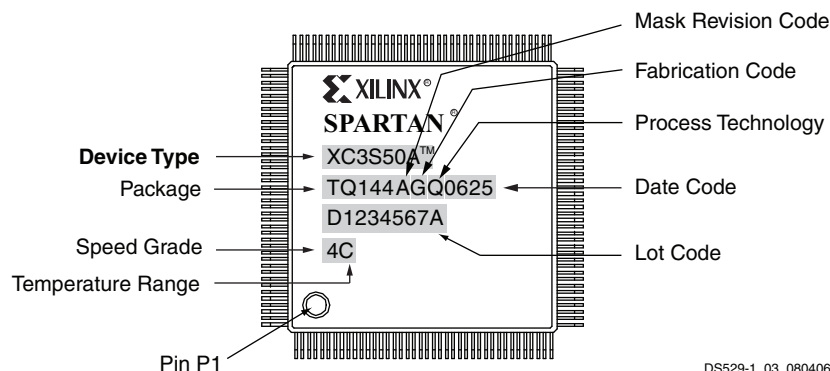


Figure 2: Spartan-3A QFP Package Marking Example

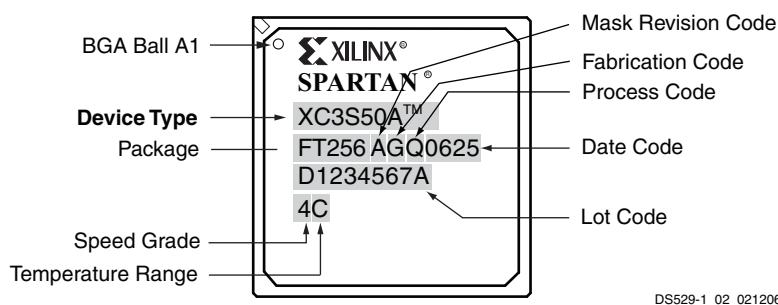


Figure 3: Spartan-3A BGA Package Marking Example

Power Supply Specifications

Table 5: Supply Voltage Thresholds for Power-On Reset

Symbol	Description	Min	Max	Units
V_{CCINTT}	Threshold for the V_{CCINT} supply	0.4	1.0	V
V_{CCAUXT}	Threshold for the V_{CCAUX} supply	1.0	2.0	V
V_{CCO2T}	Threshold for the V_{CCO} Bank 2 supply	1.0	2.0	V

Notes:

1. V_{CCINT} , V_{CCAUX} , and V_{CCO} supplies to the FPGA can be applied in any order. However, the FPGA's configuration source (Platform Flash, SPI Flash, parallel NOR Flash, microcontroller) might have specific requirements. Check the data sheet for the attached configuration source. Apply V_{CCINT} last for lowest overall power consumption (see [UG331](#) chapter "Powering Spartan-3 Generation FPGAs" for more information).
2. To ensure successful power-on, V_{CCINT} , V_{CCO} Bank 2, and V_{CCAUX} supplies must rise through their respective threshold-voltage ranges with no dips at any point.

Table 6: Supply Voltage Ramp Rate

Symbol	Description	Min	Max	Units
V_{CCINTR}	Ramp rate from GND to valid V_{CCINT} supply level	0.2	100	ms
V_{CCAUXR}	Ramp rate from GND to valid V_{CCAUX} supply level	0.2	100	ms
V_{CCO2R}	Ramp rate from GND to valid V_{CCO} Bank 2 supply level	0.2	100	ms

Notes:

1. V_{CCINT} , V_{CCAUX} , and V_{CCO} supplies to the FPGA can be applied in any order. However, the FPGA's configuration source (Platform Flash, SPI Flash, parallel NOR Flash, microcontroller) might have specific requirements. Check the data sheet for the attached configuration source. Apply V_{CCINT} last for lowest overall power consumption (see [UG331](#) chapter "Powering Spartan-3 Generation FPGAs" for more information).
2. To ensure successful power-on, V_{CCINT} , V_{CCO} Bank 2, and V_{CCAUX} supplies must rise through their respective threshold-voltage ranges with no dips at any point.

Table 7: Supply Voltage Levels Necessary for Preserving CMOS Configuration Latch (CCL) Contents and RAM Data

Symbol	Description	Min	Units
V_{DRINT}	V_{CCINT} level required to retain CMOS Configuration Latch (CCL) and RAM data	1.0	V
V_{DRAUX}	V_{CCAUX} level required to retain CMOS Configuration Latch (CCL) and RAM data	2.0	V

General Recommended Operating Conditions

Table 8: General Recommended Operating Conditions

Symbol	Description			Min	Nominal	Max	Units
T _J	Junction temperature	Commercial		0	—	85	°C
		Industrial		−40	—	100	°C
V _{CCINT}	Internal supply voltage			1.14	1.20	1.26	V
V _{CCO} ⁽¹⁾	Output driver supply voltage			1.10	—	3.60	V
V _{CCAUX}	Auxiliary supply voltage ⁽²⁾	V _{CCAUX} = 2.5		2.25	2.50	2.75	V
		V _{CCAUX} = 3.3		3.00	3.30	3.60	V
V _{IN}	Input voltage ⁽³⁾	PCI IOSTANDARD		−0.5	—	V _{CCO} +0.5	V
		All other IOSTANDARDS	IP or IO_#	−0.5	—	4.10	V
			IO_Lxxy_# ⁽⁴⁾	−0.5	—	4.10	V
T _{IN}	Input signal transition time ⁽⁵⁾			—	—	500	ns

Notes:

1. This V_{CCO} range spans the lowest and highest operating voltages for all supported I/O standards. [Table 11](#) lists the recommended V_{CCO} range specific to each of the single-ended I/O standards, and [Table 13](#) lists that specific to the differential standards.
2. Define V_{CCAUX} selection using CONFIG VCCAUX constraint.
3. See [XAPP459](#), “Eliminating I/O Coupling Effects when Interfacing Large-Swing Single-Ended Signals to User I/O Pins.”
4. For single-ended signals that are placed on a differential-capable I/O, V_{IN} of −0.2V to −0.5V is supported but can cause increased leakage between the two pins. See *Parasitic Leakage* in [UG331](#), *Spartan-3 Generation FPGA User Guide*.
5. Measured between 10% and 90% V_{CCO} . Follow [Signal Integrity](#) recommendations.

Switching Characteristics

All Spartan-3A FPGAs ship in two speed grades: –4 and the higher performance –5. Switching characteristics in this document are designated as Advance, Preliminary, or Production, as shown in Table 16. Each category is defined as follows:

Advance: These specifications are based on simulations only and are typically available soon after establishing FPGA specifications. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary: These specifications are based on complete early silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting preliminary delays is greatly reduced compared to Advance data.

Production: These specifications are approved once enough production silicon of a particular device has been characterized to provide full correlation between speed files and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

Software Version Requirements

Production-quality systems must use FPGA designs compiled using a speed file designated as PRODUCTION status. FPGA designs using a less mature speed file designation should only be used during system prototyping or pre-production qualification. FPGA designs with speed files designated as Advance or Preliminary should not be used in a production-quality system.

Whenever a speed file designation changes, as a device matures toward Production status, rerun the latest Xilinx® ISE® software on the FPGA design to ensure that the FPGA design incorporates the latest timing information and software updates.

All parameter limits are representative of worst-case supply voltage and junction temperature conditions. **Unless otherwise noted, the published parameter values apply to all Spartan-3A devices. AC and DC characteristics are specified using the same numbers for both commercial and industrial grades.**

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Timing parameters and their representative values are selected for inclusion below either because they are important as general design requirements or they indicate fundamental device performance characteristics. The Spartan-3A FPGA speed files (v1.41), part of the Xilinx Development Software, are the original source for many but not all of the values. The speed grade designations for these files are shown in Table 16. For more complete, more precise, and worst-case data, use the values reported by the Xilinx static timing analyzer (TRACE in the Xilinx development software) and back-annotated to the simulation netlist.

Table 16: Spartan-3A v1.41 Speed Grade Designation

Device	Advance	Preliminary	Production
XC3S50A			-4, -5
XC3S200A			-4, -5
XC3S400A			-4, -5
XC3S700A			-4, -5
XC3S1400A			-4, -5

Table 17 provides the recent history of the Spartan-3A FPGA speed files.

Table 17: Spartan-3A Speed File Version History

Version	ISE Release	Description
1.41	ISE 10.1.03	Updated Automotive output delays
1.40	ISE 10.1.02	Updated Automotive input delays.
1.39	ISE 10.1.01	Added Automotive parts.
1.38	ISE 9.2.03i	Added Absolute Minimum values.
1.37	ISE 9.2.01i	Updated pin-to-pin setup and hold times (Table 19), TMDs output adjustment (Table 26) multiplier setup/hold times (Table 34), and block RAM clock width (Table 35).
1.36	ISE 9.2i; previously available via Answer Record AR24992	XC3S400A, all speed grades and all temperature grades, upgraded to Production
1.35	Answer Record AR24992	XC3S50A, XC3S200A, XC3S700A, XC3S1400A, all speed grades and all temperature grades, upgraded to Production.
1.34	ISE 9.1.03i	XC3S700A and XC3S1400A -4 speed grade upgraded to Production. Updated pin-to-pin timing numbers.

Table 22: Propagation Times for the IOB Input Path(Continued)

Symbol	Description	Conditions	DELAY_VALUE	Device	Speed Grade		Units
					-5	-4	
					Max	Max	
T _{IOPLID}	The time it takes for data to travel from the Input pin through the IFF latch to the I output with the input delay programmed	LVCMOS25 ⁽²⁾	5	XC3S400A	3.55	4.18	ns
			6		4.34	5.03	ns
			7		5.09	5.88	ns
			8		5.58	6.42	ns
			1	XC3S700A	1.96	2.18	ns
			2		2.76	3.06	ns
			3		3.45	3.95	ns
			4		3.97	4.54	ns
			5		3.83	4.37	ns
			6		4.74	5.42	ns
			7		5.53	6.33	ns
			8		6.06	6.96	ns
			1	XC3S1400A	1.93	2.40	ns
			2		2.69	3.15	ns
			3		3.52	3.99	ns
			4		3.89	4.55	ns
			5		3.95	4.42	ns
			6		4.53	5.32	ns
			7		5.30	6.21	ns
			8		5.83	6.80	ns

Notes:

1. The numbers in this table are tested using the methodology presented in [Table 27](#) and are based on the operating conditions set forth in [Table 8](#) and [Table 11](#).
2. This propagation time requires adjustment whenever a signal standard other than LVCMOS25 is assigned to the data Input. When this is true, *add* the appropriate Input adjustment from [Table 23](#).

Output Timing Adjustments

Table 26: Output Timing Adjustments for IOB

Convert Output Time from LVCMOS25 with 12mA Drive and Fast Slew Rate to the Following Signal Standard (IOSTANDARD)			Add the Adjustment Below		Units
			Speed Grade		
			-5	-4	
Single-Ended Standards					
LVTTL	Slow	2 mA	5.58	5.58	ns
		4 mA	3.16	3.16	ns
		6 mA	3.17	3.17	ns
		8 mA	2.09	2.09	ns
		12 mA	1.62	1.62	ns
		16 mA	1.24	1.24	ns
		24 mA	2.74 ⁽³⁾	2.74 ⁽³⁾	ns
	Fast	2 mA	3.03	3.03	ns
		4 mA	1.71	1.71	ns
		6 mA	1.71	1.71	ns
		8 mA	0.53	0.53	ns
		12 mA	0.53	0.53	ns
		16 mA	0.59	0.59	ns
		24 mA	0.60	0.60	ns
	QuietIO	2 mA	27.67	27.67	ns
		4 mA	27.67	27.67	ns
		6 mA	27.67	27.67	ns
		8 mA	16.71	16.71	ns
		12 mA	16.67	16.67	ns
		16 mA	16.22	16.22	ns
		24 mA	12.11	12.11	ns

Table 26: Output Timing Adjustments for IOB(Continued)

Convert Output Time from LVC MOS25 with 12mA Drive and Fast Slew Rate to the Following Signal Standard (IOSTANDARD)			Add the Adjustment Below		Units
			Speed Grade		
			-5	-4	
LVC MOS33	Slow	2 mA	5.58	5.58	ns
		4 mA	3.17	3.17	ns
		6 mA	3.17	3.17	ns
		8 mA	2.09	2.09	ns
		12 mA	1.24	1.24	ns
		16 mA	1.15	1.15	ns
		24 mA	2.55 ⁽³⁾	2.55 ⁽³⁾	ns
	Fast	2 mA	3.02	3.02	ns
		4 mA	1.71	1.71	ns
		6 mA	1.72	1.72	ns
		8 mA	0.53	0.53	ns
		12 mA	0.59	0.59	ns
		16 mA	0.59	0.59	ns
		24 mA	0.51	0.51	ns
	QuietIO	2 mA	27.67	27.67	ns
		4 mA	27.67	27.67	ns
		6 mA	27.67	27.67	ns
		8 mA	16.71	16.71	ns
		12 mA	16.29	16.29	ns
		16 mA	16.18	16.18	ns
		24 mA	12.11	12.11	ns

Table 26: Output Timing Adjustments for IOB(Continued)

Convert Output Time from LVCMOS25 with 12mA Drive and Fast Slew Rate to the Following Signal Standard (IOSTANDARD)	Add the Adjustment Below		Units
	Speed Grade		
	-5	-4	
Differential Standards			
LVDS_25	1.16	1.16	ns
LVDS_33	0.46	0.46	ns
BLVDS_25	0.11	0.11	ns
MINI_LVDS_25	0.75	0.75	ns
MINI_LVDS_33	0.40	0.40	ns
LVPECL_25	Input Only		
LVPECL_33			
RSDS_25	1.42	1.42	ns
RSDS_33	0.58	0.58	ns
TMDS_33	0.46	0.46	ns
PPDS_25	1.07	1.07	ns
PPDS_33	0.63	0.63	ns
DIFF_HSTL_I_18	0.43	0.43	ns
DIFF_HSTL_II_18	0.41	0.41	ns
DIFF_HSTL_III_18	0.36	0.36	ns
DIFF_HSTL_I	1.01	1.01	ns
DIFF_HSTL_III	0.54	0.54	ns
DIFF_SSTL18_I	0.49	0.49	ns
DIFF_SSTL18_II	0.41	0.41	ns
DIFF_SSTL2_I	0.82	0.82	ns
DIFF_SSTL2_II	0.09	0.09	ns
DIFF_SSTL3_I	1.16	1.16	ns
DIFF_SSTL3_II	0.28	0.28	ns

Notes:

1. The numbers in this table are tested using the methodology presented in [Table 27](#) and are based on the operating conditions set forth in [Table 8](#), [Table 11](#), and [Table 13](#).
2. These adjustments are used to convert output- and three-state-path times originally specified for the LVCMOS25 standard with 12 mA drive and Fast slew rate to times that correspond to other signal standards. Do not adjust times that measure when outputs go into a high-impedance state.
3. Note that 16 mA drive is faster than 24 mA drive for the Slow slew rate.

Configuration Clock (CCLK) Characteristics

Table 46: Master Mode CCLK Output Period by *ConfigRate* Option Setting

Symbol	Description	ConfigRate Setting	Temperature Range	Minimum	Maximum	Units
T _{CCLK1}	CCLK clock period by ConfigRate setting	1 <i>(power-on value)</i>	Commercial	1,254	2,500	ns
			Industrial	1,180		ns
T _{CCLK3}		3	Commercial	413	833	ns
			Industrial	390		ns
T _{CCLK6}		6 (default)	Commercial	207	417	ns
			Industrial	195		ns
T _{CCLK7}		7	Commercial	178	357	ns
			Industrial	168		ns
T _{CCLK8}		8	Commercial	156	313	ns
			Industrial	147		ns
T _{CCLK10}		10	Commercial	123	250	ns
			Industrial	116		ns
T _{CCLK12}		12	Commercial	103	208	ns
			Industrial	97		ns
T _{CCLK13}		13	Commercial	93	192	ns
			Industrial	88		ns
T _{CCLK17}		17	Commercial	72	147	ns
			Industrial	68		ns
T _{CCLK22}		22	Commercial	54	114	ns
			Industrial	51		ns
T _{CCLK25}		25	Commercial	47	100	ns
			Industrial	45		ns
T _{CCLK27}		27	Commercial	44	93	ns
			Industrial	42		ns
T _{CCLK33}		33	Commercial	36	76	ns
			Industrial	34		ns
T _{CCLK44}		44	Commercial	26	57	ns
			Industrial	25		ns
T _{CCLK50}		50	Commercial	22	50	ns
			Industrial	21		ns
T _{CCLK100}		100	Commercial	11.2	25	ns
			Industrial	10.6		ns

Notes:

1. Set the **ConfigRate** option value when generating a configuration bitstream.

Table 47: Master Mode CCLK Output Frequency by ConfigRate Option Setting

Symbol	Description	ConfigRate Setting	Temperature Range	Minimum	Maximum	Units
F _{CCLK1}	Equivalent CCLK clock frequency by ConfigRate setting	1 <i>(power-on value)</i>	Commercial	0.400	0.797	MHz
			Industrial		0.847	MHz
F _{CCLK3}		3	Commercial	1.20	2.42	MHz
			Industrial		2.57	MHz
F _{CCLK6}		6 (default)	Commercial	2.40	4.83	MHz
			Industrial		5.13	MHz
F _{CCLK7}		7	Commercial	2.80	5.61	MHz
			Industrial		5.96	MHz
F _{CCLK8}		8	Commercial	3.20	6.41	MHz
			Industrial		6.81	MHz
F _{CCLK10}		10	Commercial	4.00	8.12	MHz
			Industrial		8.63	MHz
F _{CCLK12}		12	Commercial	4.80	9.70	MHz
			Industrial		10.31	MHz
F _{CCLK13}		13	Commercial	5.20	10.69	MHz
			Industrial		11.37	MHz
F _{CCLK17}		17	Commercial	6.80	13.74	MHz
			Industrial		14.61	MHz
F _{CCLK22}		22	Commercial	8.80	18.44	MHz
			Industrial		19.61	MHz
F _{CCLK25}	25	Commercial	10.00	20.90	MHz	
		Industrial		22.23	MHz	
F _{CCLK27}	27	Commercial	10.80	22.39	MHz	
		Industrial		23.81	MHz	
F _{CCLK33}	33	Commercial	13.20	27.48	MHz	
		Industrial		29.23	MHz	
F _{CCLK44}	44	Commercial	17.60	37.60	MHz	
		Industrial		40.00	MHz	
F _{CCLK50}	50	Commercial	20.00	44.80	MHz	
		Industrial		47.66	MHz	
F _{CCLK100}	100	Commercial	40.00	88.68	MHz	
		Industrial		94.34	MHz	

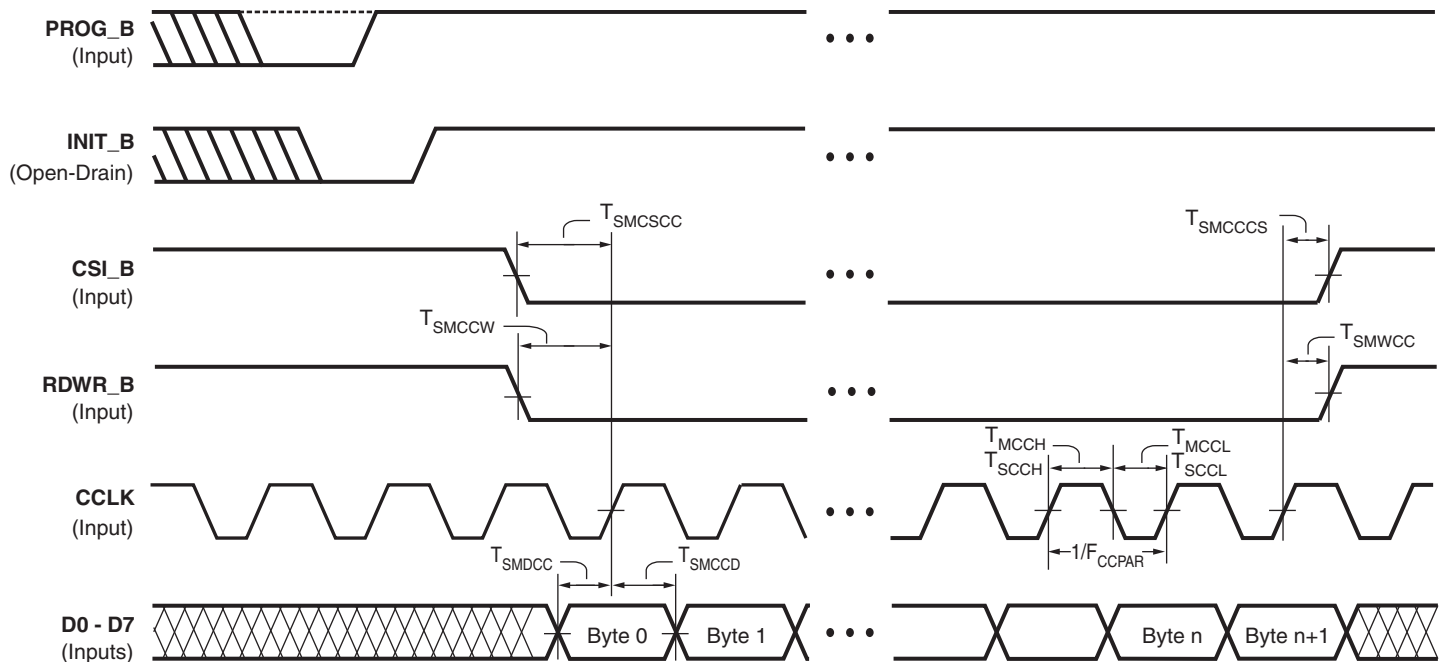
Table 48: Master Mode CCLK Output Minimum Low and High Time

Symbol	Description		ConfigRate Setting																Units
			1	3	6	7	8	10	12	13	17	22	25	27	33	44	50	100	
T _{MCCL} , T _{MCC} H	Master Mode CCLK Minimum Low and High Time	Commercial	595	196	98.3	84.5	74.1	58.4	48.9	44.1	34.2	25.6	22.3	20.9	17.1	12.3	10.4	5.3	ns
		Industrial	560	185	92.6	79.8	69.8	55.0	46.0	41.8	32.3	24.2	21.4	20.0	16.2	11.9	10.0	5.0	ns

Table 49: Slave Mode CCLK Input Low and High Time

Symbol	Description	Min	Max	Units
T _{SCCL} , T _{SCCH}	CCLK Low and High time	5	∞	ns

Slave Parallel Mode Timing

**Notes:**

1. It is possible to abort configuration by pulling CSI_B Low in a given CCLK cycle, then switching RDWR_B Low or High in any subsequent cycle for which CSI_B remains Low. The RDWR_B pin asynchronously controls the driver impedance of the D0 - D7 bus. When RDWR_B switches High, be careful to avoid contention on the D0 - D7 bus.
2. To pause configuration, pause CCLK instead of de-asserting CSI_B. See [UG332](#) Chapter 7 section "Non-Continuous SelectMAP Data Loading" for more details.

Figure 13: Waveforms for Slave Parallel Configuration

Table 51: Timing for the Slave Parallel Configuration Mode

Symbol	Description		All Speed Grades		Units
			Min	Max	
Setup Times					
T _{SMDCC} ⁽²⁾	The time from the setup of data at the D0-D7 pins to the rising transition at the CCLK pin		7	—	ns
T _{SMCSCC}	Setup time on the CSI_B pin before the rising transition at the CCLK pin		7	—	ns
T _{SMCCW}	Setup time on the RDWR_B pin before the rising transition at the CCLK pin		15	—	ns
Hold Times					
T _{SMCCD}	The time from the rising transition at the CCLK pin to the point when data is last held at the D0-D7 pins		1.0	—	ns
T _{SMCCCS}	The time from the rising transition at the CCLK pin to the point when a logic level is last held at the CSO_B pin		0	—	ns
T _{SMWCC}	The time from the rising transition at the CCLK pin to the point when a logic level is last held at the RDWR_B pin		0	—	ns
Clock Timing					
T _{CCH}	The High pulse width at the CCLK input pin		5	—	ns
T _{CCL}	The Low pulse width at the CCLK input pin		5	—	ns
F _{CCPAR}	Frequency of the clock signal at the CCLK input pin	No bitstream compression	0	80	MHz
		With bitstream compression	0	80	MHz

Notes:

1. The numbers in this table are based on the operating conditions set forth in [Table 8](#).
2. Some Xilinx documents refer to Parallel modes as "SelectMAP" modes.

User I/Os by Bank

Table 64 indicates how the 68 available user-I/O pins are distributed between the four I/O banks on the VQ100 package.

Table 64: User I/Os Per Bank for the XC3S50A and XC3S200A in the VQ100 Package

Package Edge	I/O Bank	Maximum I/O	All Possible I/O Pins by Type				
			I/O	INPUT	DUAL	VREF	CLK
Top	0	15	3	1	1	3	7
Right	1	13	6	0	0	1	6
Bottom	2	26	2	0	19	1	4
Left	3	14	6	1	0	1	6
TOTAL		68	17	2	20	6	23

Footprint Migration Differences

The XC3S50A and XC3S200 have common VQ100 pinouts except for some differences in alignment of differential I/O pairs.

Differential I/O Alignment Differences

Some differential I/O pairs in the VQ100 on the XC3S50A FPGA are aligned differently than the corresponding pairs on the XC3S200A FPGAs, as shown in Table 65. All the mismatched pairs are in I/O Bank 2. These differences are indicated with the black diamond character (◆) in the footprint diagrams Figure 17 and Figure 18.

Table 65: Differential I/O Differences in VQ100

VQ100 Pin	Bank	XC3S50A	XC3S200A
P29	2	IIO_L04P_2/VS2	IO_L03N_2/VS2
P30		IO_L03N_2/VS1	IO_L04P_2/VS1
P33		IO_L06P_2	IO_L05N_2
P34		IO_L05N_2/D7	IO_L06P_2/D7
P51		IO_L11N_2/D0/DIN/MISO	IO_L12P_2/D0/DIN/MISO
P52		IO_L12P_2/D1	IO_L11N_2/D1

VQ100 Footprint (XC3S50A)

Note pin 1 indicator in top-left corner and logo orientation.

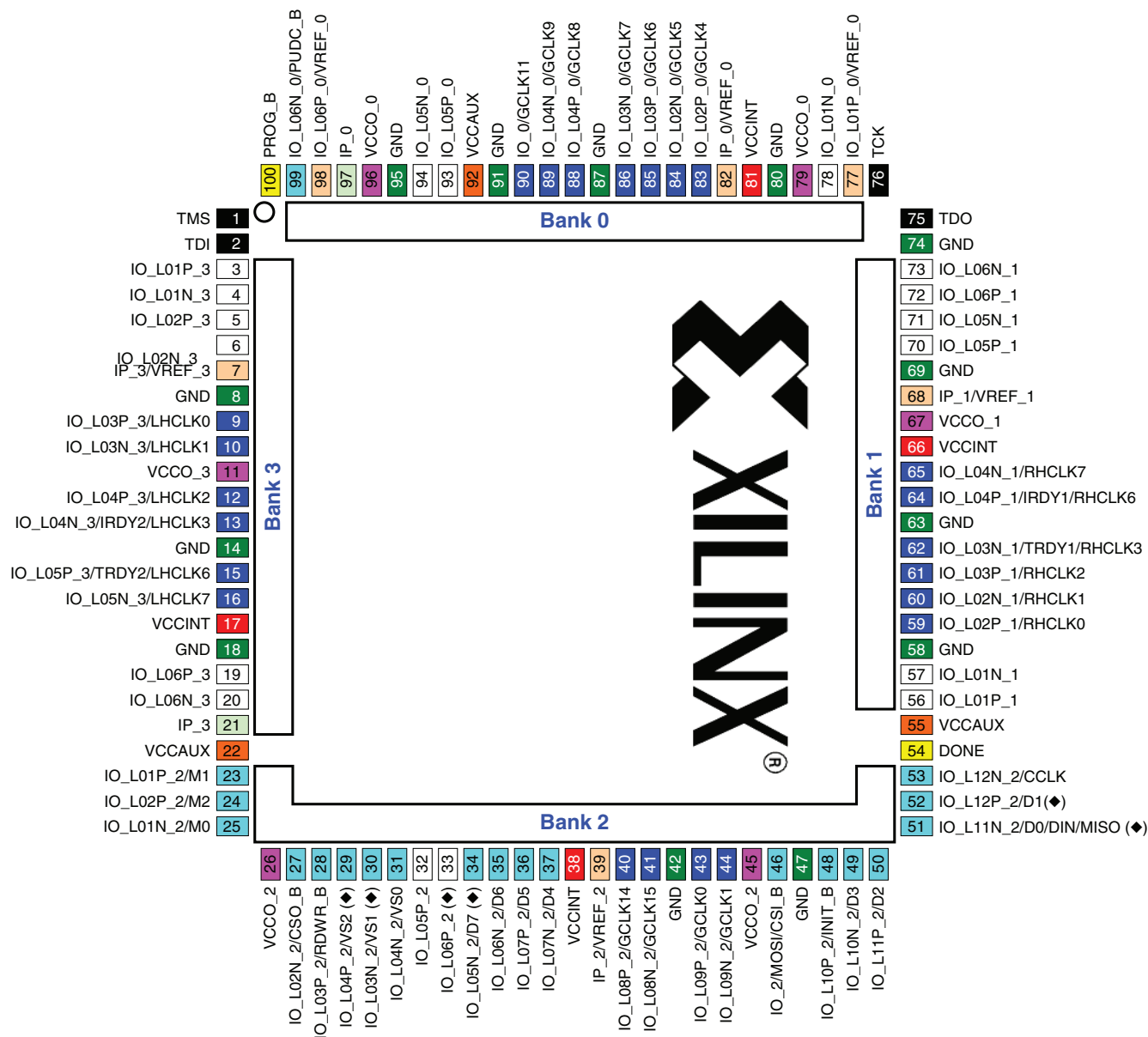


Figure 17: VQ100 Package Footprint - XC3S50A (Top View)

17	IO: Unrestricted, general-purpose user I/O	20	DUAL: Configuration pins, then possible user I/O	6	VREF: User I/O or input voltage reference for bank
2	INPUT: Unrestricted, general-purpose input pin	23	CLK: User I/O, input, or global buffer input	6	VCCO: Output voltage supply for bank
2	CONFIG: Dedicated configuration pins	4	JTAG: Dedicated JTAG port pins	4	VCCINT: Internal core supply voltage (+1.2V)
0	N.C.: Not connected	13	GND: Ground	3	VCCAUX: Auxiliary supply voltage

Table 68: Spartan-3A FT256 Pinout (XC3S50A, XC3S200A, XC3S400) (Continued)

Bank	XC3S50A	XC3S200A XC3S400A	FT256 Ball	Type
3	IO_L14N_3/ LHCLK5	IO_L14N_3/ LHCLK5	J1	LHCLK
3	IO_L14P_3/ LHCLK4	IO_L14P_3/ LHCLK4	J2	LHCLK
3	IO_L15N_3/ LHCLK7	IO_L15N_3/ LHCLK7	K1	LHCLK
3	IO_L15P_3/ TRDY2/LHCLK6	IO_L15P_3/ TRDY2/LHCLK6	K3	LHCLK
3	N.C. (◆)	IO_L16N_3	L2	I/O
3	N.C. (◆)	IO_L16P_3/ VREF_3	L1	VREF
3	N.C. (◆)	IO_L17N_3	J6	I/O
3	N.C. (◆)	IO_L17P_3	J4	I/O
3	N.C. (◆)	IO_L18N_3	L3	I/O
3	N.C. (◆)	IO_L18P_3	K4	I/O
3	N.C. (◆)	IO_L19N_3	L4	I/O
3	N.C. (◆)	IO_L19P_3	M3	I/O
3	IO_L20N_3	IO_L20N_3	N1	I/O
3	IO_L20P_3	IO_L20P_3	M1	I/O
3	IO_L22N_3	IO_L22N_3	P1	I/O
3	IO_L22P_3	IO_L22P_3	N2	I/O
3	IO_L23N_3	IO_L23N_3	P2	I/O
3	IO_L23P_3	IO_L23P_3	R1	I/O
3	IO_L24N_3	IO_L24N_3	M4	I/O
3	IO_L24P_3	IO_L24P_3	N3	I/O
3	IP_L04N_3/ VREF_3	IP_L04N_3/ VREF_3	F4	VREF
3	IP_L04P_3	IP_L04P_3	E4	INPUT
3	N.C. (◆)	IP_L06N_3/ VREF_3	G5	VREF
3	N.C. (◆)	IP_L06P_3	G6	INPUT
3	IP_L13N_3	IP_L13N_3	J7	INPUT
3	IP_L13P_3	IP_L13P_3	H7	INPUT
3	IP_L21N_3	IP_L21N_3	K6	INPUT
3	IP_L21P_3	IP_L21P_3	K5	INPUT
3	IP_L25N_3/ VREF_3	IP_L25N_3/ VREF_3	L6	VREF
3	IP_L25P_3	IP_L25P_3	L5	INPUT
3	VCCO_3	VCCO_3	D2	VCCO
3	VCCO_3	VCCO_3	H2	VCCO
3	VCCO_3	VCCO_3	J5	VCCO
3	VCCO_3	VCCO_3	M2	VCCO
GND	GND	GND	A1	GND
GND	GND	GND	A16	GND
GND	GND	GND	B7	GND

Table 68: Spartan-3A FT256 Pinout (XC3S50A, XC3S200A, XC3S400) (Continued)

Bank	XC3S50A	XC3S200A XC3S400A	FT256 Ball	Type
GND	GND	GND	B11	GND
GND	GND	GND	C3	GND
GND	GND	GND	C14	GND
GND	GND	GND	E5	GND
GND	GND	GND	E12	GND
GND	GND	GND	F2	GND
GND	GND	GND	F6	GND
GND	GND	GND	G8	GND
GND	GND	GND	G10	GND
GND	GND	GND	G15	GND
GND	GND	GND	H9	GND
GND	GND	GND	J8	GND
GND	GND	GND	K2	GND
GND	GND	GND	K7	GND
GND	GND	GND	K9	GND
GND	GND	GND	L11	GND
GND	GND	GND	L15	GND
GND	GND	GND	M5	GND
GND	GND	GND	M12	GND
GND	GND	GND	P3	GND
GND	GND	GND	P14	GND
GND	GND	GND	R6	GND
GND	GND	GND	R10	GND
GND	GND	GND	T1	GND
GND	GND	GND	T16	GND
VCCAUX	SUSPEND	SUSPEND	R16	PWR MGMT
VCCAUX	DONE	DONE	T15	CONFIG
VCCAUX	PROG_B	PROG_B	A2	CONFIG
VCCAUX	TCK	TCK	A15	JTAG
VCCAUX	TDI	TDI	B1	JTAG
VCCAUX	TDO	TDO	B16	JTAG
VCCAUX	TMS	TMS	B2	JTAG
VCCAUX	VCCAUX	VCCAUX	E11	VCCAUX
VCCAUX	VCCAUX	VCCAUX	F5	VCCAUX
VCCAUX	VCCAUX	VCCAUX	L12	VCCAUX
VCCAUX	VCCAUX	VCCAUX	M6	VCCAUX
VCCINT	VCCINT	VCCINT	G7	VCCINT
VCCINT	VCCINT	VCCINT	G9	VCCINT
VCCINT	VCCINT	VCCINT	H8	VCCINT
VCCINT	VCCINT	VCCINT	J9	VCCINT

Table 69: Spartan-3A FT256 Pinout (XC3S700A,

Bank	XC3S700A XC3S1400A	FT256 Ball	Type
1	IO_L20P_1/A18	E14	DUAL
1	IO_L22N_1/A21	D15	DUAL
1	IO_L22P_1/A20	D16	DUAL
1	IO_L23N_1/A23	D14	DUAL
1	IO_L23P_1/A22	E13	DUAL
1	IO_L24N_1/A25	C15	DUAL
1	IO_L24P_1/A24	C16	DUAL
1	IP_1/VREF_1	H12	VREF
1	IP_1/VREF_1	J14	VREF
1	IP_1/VREF_1	M13	VREF
1	IP_1/VREF_1	M14	VREF
1	VCCO_1	E15	VCCO
1	VCCO_1	J15	VCCO
1	VCCO_1	N15	VCCO
2	IO_L01N_2/M0	P4	DUAL
2	IO_L01P_2/M1	N4	DUAL
2	IO_L02N_2/CSO_B	T2	DUAL
2	IO_L02P_2/M2	R2	DUAL
2	IO_L03N_2/VS2	T3	DUAL
2	IO_L03P_2/RDWR_B	R3	DUAL
2	IO_L04N_2/VS0	P5	DUAL
2	IO_L04P_2/VS1	N6	DUAL
2	IO_L05N_2	R5	I/O
2	IO_L05P_2	T4	I/O
2	IO_L06N_2/D6	T6	DUAL
2	IO_L06P_2/D7	T5	DUAL
2	IO_L08N_2/D4	N8	DUAL
2	IO_L08P_2/D5	P7	DUAL
2	IO_L09N_2/GCLK13	T7	GCLK
2	IO_L09P_2/GCLK12	R7	GCLK
2	IO_L10N_2/GCLK15	T8	GCLK
2	IO_L10P_2/GCLK14	P8	GCLK
2	IO_L11N_2/GCLK1	P9	GCLK
2	IO_L11P_2/GCLK0	N9	GCLK
2	IO_L12N_2/GCLK3	T9	GCLK
2	IO_L12P_2/GCLK2	R9	GCLK
2	IO_L14N_2/MOSI/CSI_B	P10	DUAL
2	IO_L14P_2	T10	I/O
2	IO_L15N_2/DOUT	R11	DUAL
2	IO_L15P_2/AWAKE	T11	PWRMGT

Table 69: Spartan-3A FT256 Pinout (XC3S700A,

Bank	XC3S700A XC3S1400A	FT256 Ball	Type
2	IO_L16N_2	N11	I/O
2	IO_L16P_2	P11	I/O
2	IO_L17N_2/D3	P12	DUAL
2	IO_L17P_2/INIT_B	T12	DUAL
2	IO_L18N_2/D1	R13	DUAL
2	IO_L18P_2/D2	T13	DUAL
2	IO_L19N_2	P13	I/O
2	IO_L19P_2	N12	I/O
2	IO_L20N_2/CCLK	R14	DUAL
2	IO_L20P_2/D0/DIN/MISO	T14	DUAL
2	IP_2/VREF_2	M11	VREF
2	IP_2/VREF_2	M7	VREF
2	IP_2/VREF_2	M9	VREF
2	IP_2/VREF_2	N5	VREF
2	IP_2/VREF_2	P6	VREF
2	VCCO_2	R12	VCCO
2	VCCO_2	R4	VCCO
2	VCCO_2	R8	VCCO
3	IO_L01N_3	C1	I/O
3	IO_L01P_3	C2	I/O
3	IO_L02N_3	D3	I/O
3	IO_L02P_3	D4	I/O
3	IO_L03N_3	E1	I/O
3	IO_L03P_3	D1	I/O
3	IO_L04N_3	F4	I/O
3	IO_L04P_3	E4	I/O
3	IO_L05N_3	E2	I/O
3	IO_L05P_3	E3	I/O
3	IO_L07N_3	G3	I/O
3	IO_L07P_3	F3	I/O
3	IO_L08N_3/VREF_3	G1	VREF
3	IO_L08P_3	F1	I/O
3	IO_L11N_3/LHCLK1	H1	LHCLK
3	IO_L11P_3/LHCLK0	G2	LHCLK
3	IO_L12N_3/IRDY2/LHCLK3	J3	LHCLK
3	IO_L12P_3/LHCLK2	H3	LHCLK
3	IO_L14N_3/LHCLK5	J1	LHCLK
3	IO_L14P_3/LHCLK4	J2	LHCLK
3	IO_L15N_3/LHCLK7	K1	LHCLK
3	IO_L15P_3/TRDY2/LHCLK6	K3	LHCLK

FT256 Footprint (XC3S200A, XC3S400A)

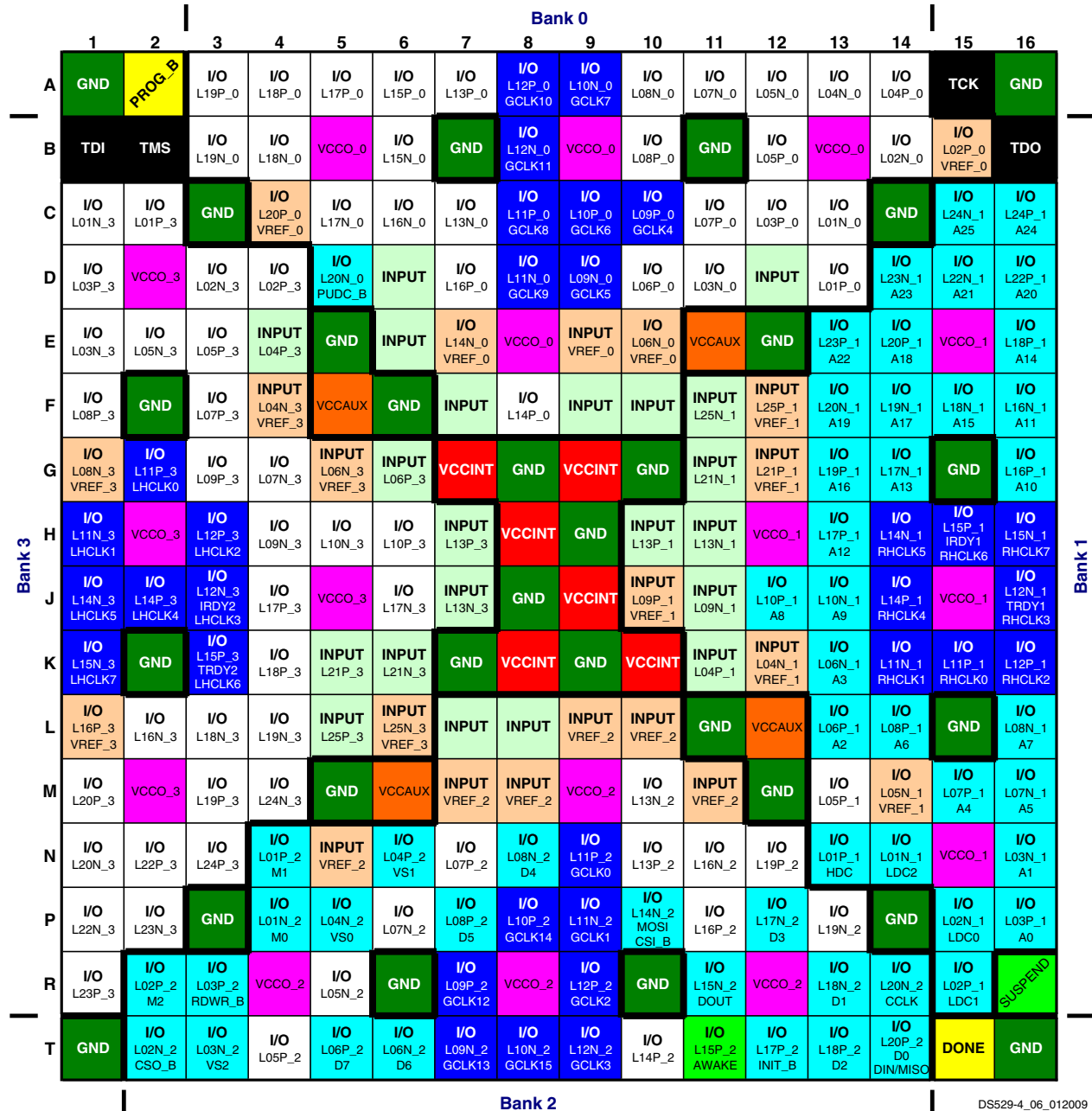


Figure 21: XC3S200A and XC3S400A FT256 Package Footprint (Top View)

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69	I/O: Unrestricted, general-purpose user I/O	51	DUAL: Configuration pins, then possible user I/O	21	VREF: User I/O or input voltage reference for bank	2	SUSPEND: Dedicated SUSPEND and dual-purpose AWAKE Power Management pins
21	INPUT: Unrestricted, general-purpose input pin	32	CLK: User I/O, input, or global buffer input	16	VCCO: Output voltage supply for bank		
2	CONFIG: Dedicated configuration pins	4	JTAG: Dedicated JTAG port pins	6	VCCINT: Internal core supply voltage (+1.2V)		
0	N.C.: Not connected	28	GND: Ground	4	VCCAUX: Auxiliary supply voltage		

Bank 0																			
11	12	13	14	15	16	17	18	19	20										
GND	I/O L13N_0	VCCAUX	I/O L07N_0	I/O L08N_0	I/O L05N_0	I/O L04N_0	I/O L01N_0	TCK	GND										
I/O L14P_0	I/O L13P_0	I/O L11P_0	GND	I/O L08P_0	VCCO_0	I/O L04P_0 VREF_0	I/O L01P_0	I/O L38N_1 A25	I/O L38P_1 A24										
I/O L14N_0	I/O L11N_0	I/O L10N_0 VREF_0	I/O L07P_0	I/O L06N_0	I/O L05P_0	I/O L02N_0	GND	I/O L37N_1 A23	I/O L37P_1 A22										
I/O L15P_0 GCLK4	I/O L12P_0	VCCO_0	I/O L10P_0	I/O L06P_0	I/O L03P_0	I/O L02P_0 VREF_0	I/O L34N_1	VCCO_1	I/O L34P_1										
I/O L15N_0 GCLK5	GND	I/O L09P_0	INPUT	I/O L03N_0	VCCAUX	TDO	I/O L33P_1	I/O L32N_1	I/O L32P_1										
INPUT	I/O L12N_0	I/O L09N_0	INPUT	GND	I/O L36N_1 A21	I/O L33N_1	I/O L30N_1 A19	I/O L29N_1 A17	I/O L29P_1 A16										
INPUT VREF_0	INPUT	INPUT	INPUT L39N_1	INPUT L39P_1 VREF_1	I/O L36P_1 A20	I/O L30P_1 A18	I/O L28P_1	GND	I/O L26N_1 A15										
INPUT	INPUT	GND	INPUT L35N_1	INPUT L35P_1	VCCO_1	I/O L28N_1	I/O L25N_1 A13	I/O L25P_1 A12	I/O L26P_1 A14										
GND	VCCINT	INPUT L31N_1	INPUT L31P_1 VREF_1	INPUT L27N_1	INPUT L27P_1	I/O L24P_1	I/O L22N_1 A11	I/O L22P_1 A10	I/O L21N_1 RHCLK7										
VCCINT	GND	VCCAUX	INPUT L23N_1	INPUT L23P_1 VREF_1	I/O L24N_1	GND	I/O L20P_1 RHCLK4	VCCO_1	I/O L21P_1 IRDY1 RHCLK6										
GND	VCCINT	INPUT L19N_1	INPUT L19P_1	I/O L16P_1 A8	I/O L16N_1 A9	I/O L20N_1 RHCLK5	I/O L18N_1 TRDY1 RHCLK3	I/O L18P_1 RHCLK2	GND										
VCCINT	GND	INPUT L15N_1	INPUT L15P_1 VREF_1	INPUT L11N_1 VREF_1	INPUT L11P_1	I/O L14P_1 A6	I/O L14N_1 A7	I/O L17P_1 RHCLK0	I/O L17N_1 RHCLK1										
GND	INPUT VREF_2	GND	INPUT VREF_1	I/O L12P_1 A2	VCCO_1	I/O L12N_1 A3	I/O L13P_1 A4	I/O L13N_1 A5	VCCAUX										
INPUT VREF_2	INPUT	INPUT	INPUT L04P_1	INPUT L04N_1 VREF_1	I/O L07P_1	I/O L07N_1	I/O L10P_1	GND	I/O L10N_1 VREF_1										
VCCO_2	I/O L19N_2	I/O L23N_2	INPUT VREF_2	SUSPEND	I/O L03N_1 A1	I/O L08N_1	I/O L08P_1	I/O L09P_1	I/O L09N_1										
INPUT	I/O L19P_2	I/O L23P_2	I/O L25N_2	I/O L27N_2	GND	I/O L03P_1 A0	I/O L05P_1	VCCO_1	I/O L05N_1										
I/O L18P_2 GCLK2	GND	I/O L22P_2 AWAKE	VCCO_2	I/O L27P_2	I/O L29N_2	I/O L31N_2	I/O L02N_1 LDC0	I/O L06P_1	I/O L06N_1										
I/O L17N_2 GCLK1	I/O L18N_2 GCLK3	I/O L22N_2 DOUT	I/O L25P_2	I/O L26N_2 D1	I/O L29P_2	I/O L31P_2	GND	I/O L02P_1 LDC1	I/O L01N_1 LDC2										
VCCO_2	I/O L20N_2 MOSI CSL_B	I/O L21N_2	I/O L24N_2 D3	GND	I/O L28N_2	VCCO_2	I/O L32P_2 D0 DIN/MISO	DONE	I/O L01P_1 HDC										
I/O L17P_2 GCLK0	I/O L20P_2	I/O L21P_2	I/O L24P_2 INIT_B	I/O L26P_2 D2	I/O L28P_2	I/O L30P_2	I/O L30N_2	I/O L32N_2 CCLK	GND										
Bank 2																			

Right Half of FG400
Package (Top View)

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FG484: 484-ball Fine-pitch Ball Grid Array

The 484-ball fine-pitch ball grid array, FG484, supports both the XC3S700A and the XC3S1400A FPGAs. There are three pinout differences, as described in [Table 86](#).

[Table 83](#) lists all the FG484 package pins. They are sorted by bank number and then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

The shaded rows indicate pinout differences between the XC3S700A and the XC3S1400A FPGAs. The XC3S700A has three unconnected balls, indicated as N.C. (No Connection) in [Table 83](#) and with the black diamond character (◆) in [Table 83](#) and [Figure 25](#).

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at

www.xilinx.com/support/documentation/data_sheets/s3a_pin.zip.

Pinout Table

Table 83: Spartan-3A FG484 Pinout

Bank	Pin Name	FG484 Ball	Type
0	IO_L01N_0	D18	I/O
0	IO_L01P_0	E17	I/O
0	IO_L02N_0	C19	I/O
0	IO_L02P_0/VREF_0	D19	VREF
0	IO_L03N_0	A20	I/O
0	IO_L03P_0	B20	I/O
0	IO_L04N_0	F15	I/O
0	IO_L04P_0	E15	I/O
0	IO_L05N_0	A18	I/O
0	IO_L05P_0	C18	I/O
0	IO_L06N_0	A19	I/O
0	IO_L06P_0/VREF_0	B19	VREF
0	IO_L07N_0	C17	I/O
0	IO_L07P_0	D17	I/O
0	IO_L08N_0	C16	I/O
0	IO_L08P_0	D16	I/O
0	IO_L09N_0	E14	I/O
0	IO_L09P_0	C14	I/O
0	IO_L10N_0	A17	I/O
0	IO_L10P_0	B17	I/O
0	IO_L11N_0	C15	I/O

Table 83: Spartan-3A FG484 Pinout(Continued)

Bank	Pin Name	FG484 Ball	Type
0	IO_L11P_0	D15	I/O
0	IO_L12N_0/VREF_0	A15	VREF
0	IO_L12P_0	A16	I/O
0	IO_L13N_0	A14	I/O
0	IO_L13P_0	B15	I/O
0	IO_L14N_0	E13	I/O
0	IO_L14P_0	F13	I/O
0	IO_L15N_0	C13	I/O
0	IO_L15P_0	D13	I/O
0	IO_L16N_0	A13	I/O
0	IO_L16P_0	B13	I/O
0	IO_L17N_0/GCLK5	E12	GCLK
0	IO_L17P_0/GCLK4	C12	GCLK
0	IO_L18N_0/GCLK7	A11	GCLK
0	IO_L18P_0/GCLK6	A12	GCLK
0	IO_L19N_0/GCLK9	C11	GCLK
0	IO_L19P_0/GCLK8	B11	GCLK
0	IO_L20N_0/GCLK11	E11	GCLK
0	IO_L20P_0/GCLK10	D11	GCLK
0	IO_L21N_0	C10	I/O
0	IO_L21P_0	A10	I/O
0	IO_L22N_0	A8	I/O
0	IO_L22P_0	A9	I/O
0	IO_L23N_0	E10	I/O
0	IO_L23P_0	D10	I/O
0	IO_L24N_0/VREF_0	C9	VREF
0	IO_L24P_0	B9	I/O
0	IO_L25N_0	C8	I/O
0	IO_L25P_0	B8	I/O
0	IO_L26N_0	A6	I/O
0	IO_L26P_0	A7	I/O
0	IO_L27N_0	C7	I/O
0	IO_L27P_0	D7	I/O
0	IO_L28N_0	A5	I/O
0	IO_L28P_0	B6	I/O
0	IO_L29N_0	D6	I/O
0	IO_L29P_0	C6	I/O
0	IO_L30N_0	D8	I/O

FG484 Footprint

Left Half of FG484 Package (Top View)

195 I/O: Unrestricted, general-purpose user I/O

60-62 INPUT: Unrestricted, general-purpose input pin

51 DUAL: Configuration pins, then possible user I/O

33-34 VREF: User I/O or input voltage reference for bank

32 CLK: User I/O, input, or clock buffer input

2 SUSPEND: Dedicated SUSPEND and dual-purpose AWAKE Power Management pins

2 CONFIG: Dedicated configuration pins

4 JTAG: Dedicated JTAG port pins

53 GND: Ground

24 VCCO: Output voltage supply for bank

15 VCCINT: Internal core supply voltage (+1.2V)

10 VCCAUX: Auxiliary supply voltage

3 N.C.: Not connected (XC3S700A only)

		Bank 0										
		1	2	3	4	5	6	7	8	9	10	11
Bank 3	A	GND	I/O L36N_0 PUDC_B	I/O L33P_0	I/O L31P_0	I/O L28N_0	I/O L26N_0	I/O L26P_0	I/O L22N_0	I/O L22P_0	I/O L21P_0	I/O L18N_0 GCLK7
	B	I/O L02P_3	I/O L36P_0 VREF_0	I/O L33N_0	I/O L31N_0	VCCO_0	I/O L28P_0	GND	I/O L25P_0	I/O L24P_0	VCCO_0	I/O L19P_0 GCLK8
	C	I/O L01P_3	I/O L02N_3	GND	PROG_B	I/O L32P_0	I/O L29P_0	I/O L27N_0	I/O L25N_0	I/O L24N_0 VREF_0	I/O L21N_0	I/O L19N_0 GCLK9
	D	I/O L06P_3	I/O L01N_3	I/O L03P_3	TMS	I/O L32N_0	I/O L29N_0	I/O L27P_0	I/O L30N_0	GND	I/O L23P_0	I/O L20P_0 GCLK10
	E	I/O L06N_3	VCCO_3	I/O L07N_3	I/O L03N_3	VCCAUX	I/O L35N_0	I/O L34P_0	INPUT	I/O L30P_0	I/O L23N_0	I/O L20N_0 GCLK11
	F	I/O L12N_3	I/O L12P_3	I/O L08P_3	I/O L07P_3	TDI	GND	I/O L35P_0	I/O L34N_0	VCCO_0	INPUT	GND
	G	I/O L13N_3	GND	I/O L13P_3	I/O L08N_3	I/O L05N_3	I/O L05P_3	INPUT	INPUT VREF_0	INPUT	INPUT	INPUT
	H	I/O L16N_3	I/O L16P_3	I/O L14N_3	I/O L14P_3	I/O L09P_3	I/O L09N_3	INPUT L04N_3 VREF_3	INPUT L04P_3	INPUT VREF_0	INPUT	VCCAUX
	J	I/O L17N_3 VREF_3	VCCO_3	I/O L17P_3	GND	I/O L10N_3	VCCO_3	INPUT L11P_3	INPUT VREF_3	GND	VCCINT	GND
	K	I/O L22P_3 LHCLK2	I/O L20N_3	I/O L20P_3	I/O L18N_3	I/O L18P_3	I/O L10P_3	INPUT L15P_3	INPUT L11N_3	VCCINT	GND	VCCINT
	L	I/O L22N_3 IRDY2 LHCLK3	GND	I/O L21N_3 LHCLK1	VCCAUX	I/O L21P_3 LHCLK0	GND	INPUT L19P_3	INPUT L15N_3 VREF_3	GND	VCCINT	GND
	M	I/O L24P_3 LHCLK4	I/O L24N_3 LHCLK5	I/O L25P_3 TRDY2 LHCLK6	I/O L25N_3 LHCLK7	I/O L30P_3	INPUT L23N_3	INPUT L23P_3	INPUT L19N_3	VCCINT	GND	VCCINT
	N	I/O L26P_3 VREF_3	VCCO_3	I/O L26N_3	I/O L30N_3	INPUT L31N_3	INPUT L31P_3	INPUT L35P_3	INPUT L27P_3	INPUT L27N_3	VCCINT	GND
	P	I/O L28P_3	I/O L28N_3	I/O L29P_3	GND	I/O L29N_3	VCCO_3	INPUT L39P_3	INPUT L35N_3	GND	GND	VCCAUX
	R	I/O L32P_3	I/O L32N_3	I/O L33P_3	I/O L33N_3	I/O L34P_3	INPUT VREF_3	INPUT L46P_3	INPUT L39N_3	INPUT	INPUT	INPUT
	T	I/O L36P_3 VREF_3	GND	I/O L36N_3	I/O L34N_3	I/O L40P_3	INPUT L46N_3 VREF_3	INPUT VREF_2	INPUT VREF_2	INPUT	INPUT VREF_2	INPUT VREF_2
	U	I/O L37P_3	I/O L37N_3	I/O L41P_3	I/O L41N_3	I/O L40N_3	GND	INPUT	INPUT	VCCO_2	INPUT	I/O L17P_2 GCLK12
	V	I/O L38P_3	VCCO_3	I/O L38N_3	I/O L43P_3	VCCAUX	I/O L01P_2 M1	INPUT	INPUT VREF_2	I/O L09P_2 RDWR_B	I/O L13P_2	I/O L17N_2 GCLK13
	W	I/O L42P_3	I/O L42N_3	I/O L43N_3	I/O L02P_2 M2	I/O L01N_2 M0	I/O L05P_2	I/O L07P_2	I/O L11P_2 VS1	I/O L09N_2 VS2	GND	VCCAUX
	Y	I/O L44P_3	I/O L44N_3	GND	I/O L02N_2 CSO_B	I/O L05N_2	I/O L07N_2	I/O L10P_2	I/O L11N_2 VS0	I/O L14P_2 D7	I/O L13N_2	I/O L16P_2 D5
	A	I/O L45P_3	I/O L45N_3	I/O L03N_2	I/O L04N_2	VCCO_2	I/O L08P_2	GND	I/O L12P_2	VCCO_2	I/O L15P_2	GND
	A	GND	I/O L03P_2	I/O L04P_2	I/O L06P_2	I/O L06N_2	I/O L08N_2	I/O L10N_2	I/O L12N_2	I/O L14N_2 D6	I/O L15N_2	I/O L16N_2 D4
		Bank 2										

Figure 25: FG484 Package Footprint (Top View)

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Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
0	IO_L34N_0	D10	I/O
0	IO_L34P_0	C10	I/O
0	IO_L35N_0	H12	I/O
0	IO_L35P_0	G12	I/O
0	IO_L36N_0	B9	I/O
0	IO_L36P_0	A9	I/O
0	IO_L37N_0	D9	I/O
0	IO_L37P_0	E10	I/O
0	IO_L38N_0	B8	I/O
0	IO_L38P_0	A8	I/O
0	IO_L39N_0	K12	I/O
0	IO_L39P_0	J12	I/O
0	IO_L40N_0	D8	I/O
0	IO_L40P_0	C8	I/O
0	IO_L41N_0	C6	I/O
0	IO_L41P_0	B6	I/O
0	IO_L42N_0	C7	I/O
0	IO_L42P_0	B7	I/O
0	IO_L43N_0	K11	I/O
0	IO_L43P_0	J11	I/O
0	IO_L44N_0	D6	I/O
0	IO_L44P_0	C5	I/O
0	IO_L45N_0	B4	I/O
0	IO_L45P_0	A4	I/O
0	IO_L46N_0	H10	I/O
0	IO_L46P_0	G10	I/O
0	IO_L47N_0	H9	I/O
0	IO_L47P_0	G9	I/O
0	IO_L48N_0	E7	I/O
0	IO_L48P_0	F7	I/O
0	IO_L51N_0	B3	I/O
0	IO_L51P_0	A3	I/O
0	IO_L52N_0/PUDC_B	G8	DUAL
0	IO_L52P_0/VREF_0	F8	VREF
0	IP_0	A5	INPUT
0	IP_0	A7	INPUT
0	IP_0	A13	INPUT
0	IP_0	A17	INPUT
0	IP_0	A23	INPUT
0	IP_0	C4	INPUT

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
0	IP_0	D12	INPUT
0	IP_0	D15	INPUT
0	IP_0	D19	INPUT
0	IP_0	E11	INPUT
0	IP_0	E18	INPUT
0	IP_0	E20	INPUT
0	IP_0	F10	INPUT
0	IP_0	G14	INPUT
0	IP_0	G16	INPUT
0	IP_0	H13	INPUT
0	IP_0	H18	INPUT
0	IP_0	J10	INPUT
0	IP_0	J13	INPUT
0	IP_0	J15	INPUT
0	IP_0/VREF_0	D7	VREF
0	IP_0/VREF_0	D14	VREF
0	IP_0/VREF_0	G11	VREF
0	IP_0/VREF_0	J17	VREF
0	N.C. (◆)	A24	N.C.
0	N.C. (◆)	B24	N.C.
0	N.C. (◆)	D5	N.C.
0	N.C. (◆)	E9	N.C.
0	N.C. (◆)	F18	N.C.
0	N.C. (◆)	E6	N.C.
0	N.C. (◆)	F9	N.C.
0	N.C. (◆)	G18	N.C.
0	VCCO_0	B5	VCCO
0	VCCO_0	B11	VCCO
0	VCCO_0	B16	VCCO
0	VCCO_0	B22	VCCO
0	VCCO_0	E8	VCCO
0	VCCO_0	E13	VCCO
0	VCCO_0	E19	VCCO
0	VCCO_0	H11	VCCO
0	VCCO_0	H16	VCCO
1	IO_L01N_1/LDC2	Y21	DUAL
1	IO_L01P_1/HDC	Y20	DUAL
1	IO_L02N_1/LDC0	AD25	DUAL
1	IO_L02P_1/LDC1	AE26	DUAL
1	IO_L03N_1/A1	AC24	DUAL

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
2	IO_L16N_2	W12	I/O
2	IO_L16P_2	V12	I/O
2	IO_L17N_2/VS2	AA12	DUAL
2	IO_L17P_2/RDWR_B	Y12	DUAL
2	IO_L18N_2	AF8	I/O
2	IO_L18P_2	AE8	I/O
2	IO_L19N_2/VS0	AF9	DUAL
2	IO_L19P_2/VS1	AE9	DUAL
2	IO_L20N_2	W13	I/O
2	IO_L20P_2	V13	I/O
2	IO_L21N_2	AC12	I/O
2	IO_L21P_2	AB12	I/O
2	IO_L22N_2/D6	AF10	DUAL
2	IO_L22P_2/D7	AE10	DUAL
2	IO_L23N_2	AC11	I/O
2	IO_L23P_2	AD11	I/O
2	IO_L24N_2/D4	AE12	DUAL
2	IO_L24P_2/D5	AF12	DUAL
2	IO_L25N_2/GCLK13	Y13	GCLK
2	IO_L25P_2/GCLK12	AA13	GCLK
2	IO_L26N_2/GCLK15	AE13	GCLK
2	IO_L26P_2/GCLK14	AF13	GCLK
2	IO_L27N_2/GCLK1	AA14	GCLK
2	IO_L27P_2/GCLK0	Y14	GCLK
2	IO_L28N_2/GCLK3	AE14	GCLK
2	IO_L28P_2/GCLK2	AF14	GCLK
2	IO_L29N_2	AC14	I/O
2	IO_L29P_2	AD14	I/O
2	IO_L30N_2/MOSI/CSI_B	AB15	DUAL
2	IO_L30P_2	AC15	I/O
2	IO_L31N_2	W15	I/O
2	IO_L31P_2	V14	I/O
2	IO_L32N_2/DOUT	AE15	DUAL
2	IO_L32P_2/AWAKE	AD15	PWR MGMT
2	IO_L33N_2	AD17	I/O
2	IO_L33P_2	AE17	I/O
2	IO_L34N_2/D3	Y15	DUAL
2	IO_L34P_2/INIT_B	AA15	DUAL
2	IO_L35N_2	U15	I/O

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
2	IO_L35P_2	V15	I/O
2	IO_L36N_2/D1	AE18	DUAL
2	IO_L36P_2/D2	AF18	DUAL
2	IO_L37N_2	AE19	I/O
2	IO_L37P_2	AF19	I/O
2	IO_L38N_2	AB16	I/O
2	IO_L38P_2	AC16	I/O
2	IO_L39N_2	AE20	I/O
2	IO_L39P_2	AF20	I/O
2	IO_L40N_2	AC19	I/O
2	IO_L40P_2	AD19	I/O
2	IO_L41N_2	AC20	I/O
2	IO_L41P_2	AD20	I/O
2	IO_L42N_2	U16	I/O
2	IO_L42P_2	V16	I/O
2	IO_L43N_2	Y17	I/O
2	IO_L43P_2	AA17	I/O
2	IO_L44N_2	AD21	I/O
2	IO_L44P_2	AE21	I/O
2	IO_L45N_2	AC21	I/O
2	IO_L45P_2	AD22	I/O
2	IO_L46N_2	V17	I/O
2	IO_L46P_2	W17	I/O
2	IO_L47N_2	AA18	I/O
2	IO_L47P_2	AB18	I/O
2	IO_L48N_2	AE23	I/O
2	IO_L48P_2	AF23	I/O
2	IO_L51N_2	AE25	I/O
2	IO_L51P_2	AF25	I/O
2	IO_L52N_2/CCLK	AE24	DUAL
2	IO_L52P_2/D0/DIN/MISO	AF24	DUAL
2	IP_2	AA19	INPUT
2	IP_2	AB13	INPUT
2	IP_2	AB17	INPUT
2	IP_2	AB20	INPUT
2	IP_2	AC7	INPUT
2	IP_2	AC13	INPUT
2	IP_2	AC17	INPUT
2	IP_2	AC18	INPUT
2	IP_2	AD9	INPUT